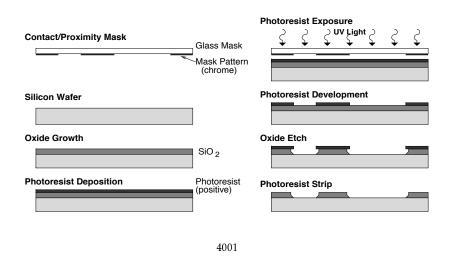
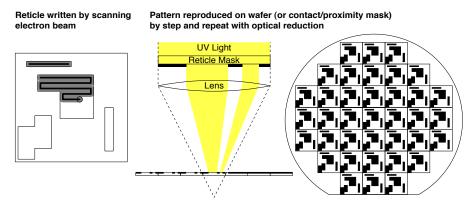
Photolithography



Mask Making

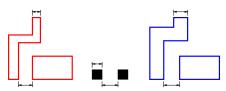


• Optical reduction allows narrower line widths.

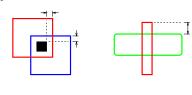
Design Rules

To prevent chip failure, designs must conform to design rules:

• Single layer rules

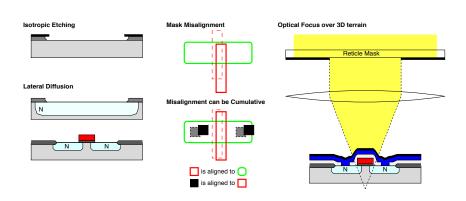


• Multi-layer rules



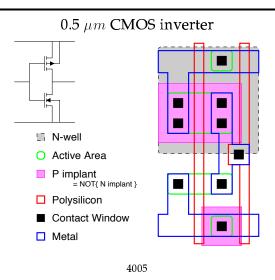
4003

Derivation of Design Rules



4002

Design Rules

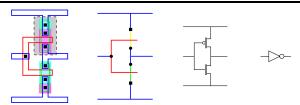


Abstraction

Levels of Abstraction

- Mask Level Design
- Laborious Technology/Process dependent.
- Design rules may change during a design!
- Transistor Level Design
- Process independent, Technology dependent.
- Gate Level Design
- Process/Technology independent.

Abstraction - Stick Diagrams



Stick diagrams give us many of the benefits of abstraction:

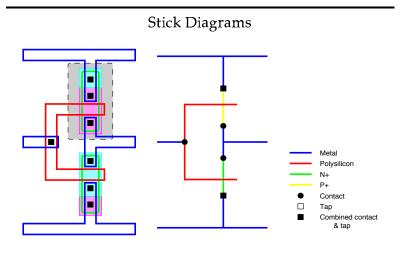
- Much easier/faster than full mask specification.
- Process independent (valid for any CMOS process).
- Easy to change.

while avoiding some of the problems:

 Optimized layout may be generated much more easily from a stick diagram than from transistor or gate level designs.¹

4007

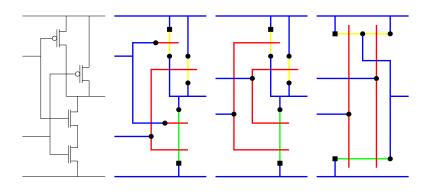
Digital CMOS Design



¹note that all IC designs must end at the mask level.

Digital CMOS Design

Stick Diagrams



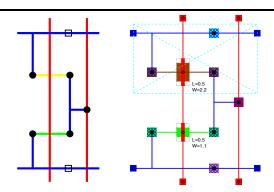
4009

Digital CMOS Design

Stick Diagrams

- Explore your Design Space.
 - Implications of crossovers.
 - Number of contacts.
 - Arrangement of devices and connections.
- Process independent layout.
- Easy to expand to a full layout for a particular process.

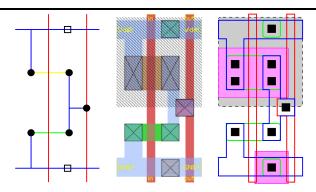
Sticks and CAD - Symbolic Capture



- Transistors are placed and explicitly sized.
- components are joined with zero width wires.
- contacts are automatically selected as required.
- A semi-automatic compaction process will create DRC correct layout.

4011

Sticks and CAD - Magic



- Log style design (sticks with width) DRC errors are flagged immediately.
 - again contacts are automatically selected as required.
- On-line DRC leads to rapid generation of correct designs.
- symbolic capture style compaction is available if desired.